



#### **DUAL P-CHANNEL ENHANCEMENT MODE MOSFET**

## **Product Summary**

Device	V <sub>(BR)DSS</sub>	/(BR)DSS RDS(ON) max				
		$61m\Omega @ V_{GS} = -4.5V$	-3.8A			
P-Channel	-12V	$81m\Omega$ @ $V_{GS} = -2.5V$	-3.3A			
		$115m\Omega @ V_{GS} = -1.8V$	-2.8A			

### **Description**

This MOSFET is designed to minimize the on-state resistance  $(R_{DS(on)})$  and yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

## **Applications**

- Load Switch
- Power Management Functions
- Portable Power Adaptors

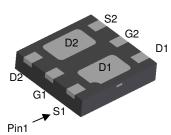
### **Features**

- Low On-Resistance
- Low Input Capacitance
- Low Profile, 0.6mm Max Height
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

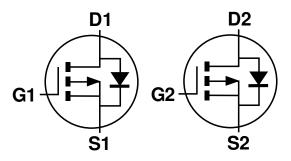
### **Mechanical Data**

- Case: U-DFN2020-6
- Case Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper Leadframe.
   Solderable per MIL-STD-202, Method 208
- Terminals Connections: See Diagram Below
- Weight: 0.0065 grams (Approximate)

# U-DFN2020-6



**Bottom View** 



Internal Schematic

### Ordering Information (Note 4)

Part Number	Case	Packaging
DMP1046UFDB -7	U-DFN2020-6	3,000/Tape & Reel
DMP1046UFDB -13	U-DFN2020-6	10,000/Tape & Reel

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

- 2. See http://www.diodes.com for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com.

# **Marking Information**

#### U-DFN2020-6



P6 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: C = 2015) M = Month (ex: 9 = September)

Date Code Key

Year	201	5	2016		2017	20	18	2019		2020	2	2021
Code	С		D		E	F	=	G		Н		
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



# Maximum Ratings (@T<sub>A</sub> = +25 °C, unless otherwise specified.)

Characteristic		Symbol	Value	Units	
Drain-Source Voltage		$V_{DSS}$	-12	V	
Gate-Source Voltage	$V_{GSS}$	±8	V		
Continuous Dusin Comment (Nets 5) V	Steady $T_A = +25$ °C $T_A = +70$ °C		I <sub>D</sub>	-3.8 -3.0	А
Continuous Drain Current (Note 5) V <sub>GS</sub> = 4.5V	t < 5s	T <sub>A</sub> = +25℃ T <sub>A</sub> = +70℃	I <sub>D</sub>	-5.0 -4.0	А
Maximum Continuous Body Diode Forward Curre	ent (Note 5)		I <sub>S</sub>	-1	Α
Pulsed Drain Current (10µs pulse, duty cycle = 1	%)	I <sub>DM</sub>	-15	Α	
Avalanche Current (L = 0.1mH)		I <sub>AS</sub>	-12	Α	
Avalanche Energy (L = 0.1mH)		Eas	8	mJ	

# **Thermal Characteristics**

Characteristic	Symbol	Value	Units		
Total Power Dissipation (Note 5)	Steady State	В	1.4	w	
Total Fower Dissipation (Note 5)	t < 5s	$P_{D}$	2.2		
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	р.,	92	°C/W	
Thermal Resistance, Junction to Ambient (Note 5)	t < 5s	$R_{\theta JA}$	55		
Thermal Resistance, Junction to Case (Note 5)	$R_{ heta JC}$	20			
Operating and Storage Temperature Range		$T_{J,}T_{STG}$	-55 to 150	°C	

Notes: 5. Device mounted on 1" x 1" FR-4 PCB with high coverage 2oz. Copper, single sided.

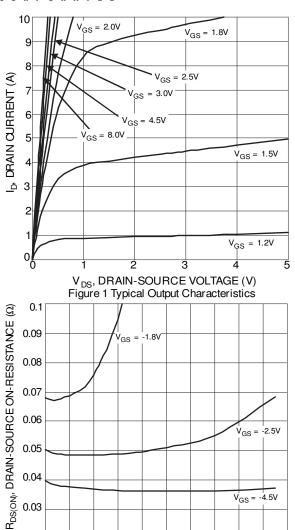
# Electrical Characteristics (@T<sub>A</sub> = +25 °C, unless otherwise specified.)

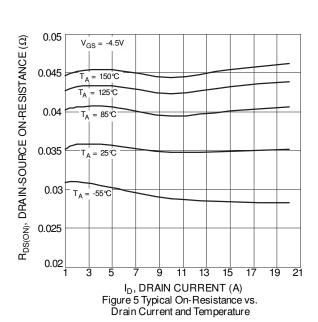
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 6)		I .		I .	l .		
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-12	-	-	V	$V_{GS} = 0V, I_{D} = -250\mu A$	
Zero Gate Voltage Drain Current T <sub>J</sub> = +25 °C	I <sub>DSS</sub>	-	-	-1.0	μA	$V_{DS} = -12V, V_{GS} = 0V$	
Gate-Source Leakage	I <sub>GSS</sub>	-	-	±100	nA	$V_{GS} = \pm 8V$ , $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 6)							
Gate Threshold Voltage	V <sub>GS(th)</sub>	-0.4	-	-1	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	
		-	37	61		$V_{GS} = -4.5V$ , $I_D = -3.6A$	
Static Drain-Source On-Resistance	R <sub>DS (ON)</sub>	-	47	81	mΩ	$V_{GS} = -2.5V, I_D = -3.2A$	
	` ′	-	63	115		V <sub>GS</sub> = -1.8V, I <sub>D</sub> = -1.0A	
Diode Forward Voltage	$V_{SD}$	-	-0.65	-1.2	V	$V_{GS} = 0V, I_S = -4.5A$	
DYNAMIC CHARACTERISTICS (Note 7)			•				
Input Capacitance	C <sub>iss</sub>	-	915	-	pF	., ., ., .,	
Output Capacitance	Coss	-	225	-	pF	$V_{DS} = -6V, V_{GS} = 0V,$ - f = 1.0MHz	
Reverse Transfer Capacitance	Crss	-	183	-	pF	1 = 1.0101112	
Gate Resistance	$R_q$	-	56.9	-	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	
Total Gate Charge (V <sub>GS</sub> = -4.5V)		-	10.7	-	nC		
Total Gate Charge (V <sub>GS</sub> = -8V)	$Q_g$		17.9		nC	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	
Gate-Source Charge	Q <sub>qs</sub>	-	1.7	-	nC	$V_{DS} = -6V, I_{D} = -4.3A$	
Gate-Drain Charge	Q <sub>qd</sub>	-	3.0	-	nC		
Turn-On Delay Time	t <sub>D(on)</sub>	-	5.7	-	ns		
Turn-On Rise Time	tr	-	11.5	-	ns	$V_{DD} = -6V, V_{GS} = -4.5V,$	
Turn-Off Delay Time	t <sub>D(off)</sub>	-	27.8	-	ns	$R_L = 1.6\Omega, R_G = 1\Omega$	
Turn-Off Fall Time	t <sub>f</sub>	-	26.4	-	ns	1	

Notes: 6. Short duration pulse test used to minimize self-heating effect.

7. Guaranteed by design. Not subject to product testing.



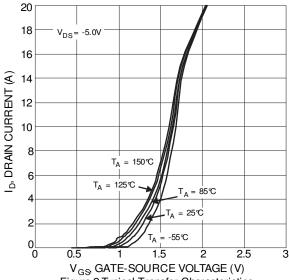


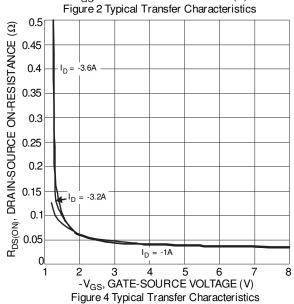


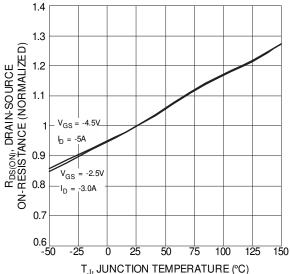
9 11 13 15 17 19

I<sub>D</sub>, DRAIN SOURCE CURRENT (A) Figure 3 Typical On-Resistance vs.

Drain Current and Gate Voltage



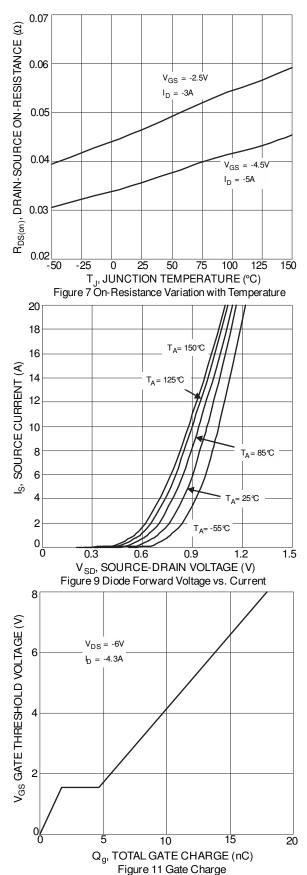


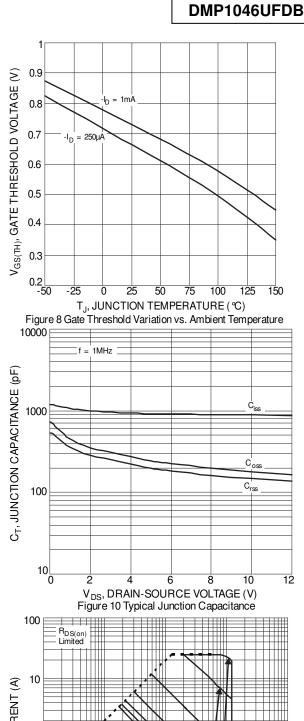


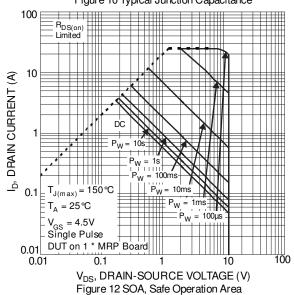
T<sub>J</sub>, JUNCTION TEMPERATURE (°C)
Figure 6 On-Resistance Variation with Temperature

0.02

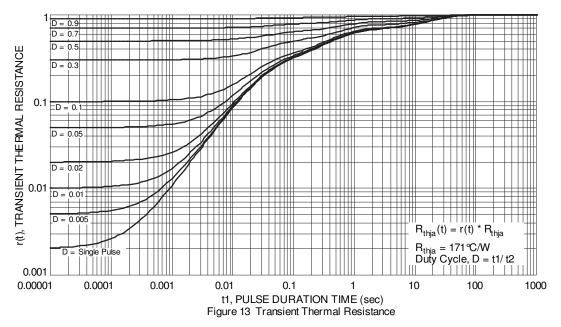






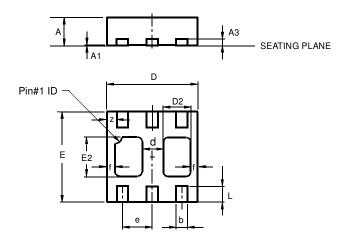






# Package Outline Dimensions

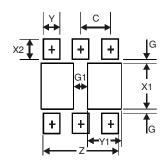
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



U-DFN2020-6								
Type B								
Dim	Min	Min Max Typ						
Α	0.545	0.605	0.575					
<b>A</b> 1	0	0.05	0.02					
<b>A3</b>	_	_	0.13					
b	0.20	0.30	0.25					
D	1.95	2.075	2.00					
d	_		0.45					
D2	0.50	0.70	0.60					
е	_		0.65					
Е	1.95	2.075	2.00					
E2	0.90	1.10	1.00					
f	_	_	0.15					
L	0.25	0.35	0.30					
Z	_		0.225					
All	Dimens	ions in	mm					

# **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	1.67
G	0.20
G1	0.40
X1	1.0
X2	0.45
Υ	0.37
Y1	0.70
С	0.65



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